

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3487149

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YEH-CHI HSU	07/28/2015
CHEN-YUEH KUNG	07/28/2015
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14828758
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<b>SIGNATURE:</b>	/Daniel R. McClure/
<b>DATE SIGNED:</b>	08/18/2015
<b>Total Attachments: 1</b>	
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## ASSIGNMENT

WHEREAS, Yeh-Chi HSU and Chen-Yueh KUNG  
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as  
described and set forth in the below identified application for United States Letters Patent:  
Title: CIRCUIT SUBSTRATE AND SEMICONDUCTOR PACKAGE STRUCTURE

Filed: \_\_\_\_\_ Serial No. \_\_\_\_\_  
Executed on: \_\_\_\_\_

WHEREAS, VIA Alliance Semiconductor Co., Ltd. of Room 301, No.2537, Jinke Road, Zhangjiang Hi-Tech Park, Shanghai 201203, P.R. China hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Yeh-Chi Hsu  
Yeh-Chi HSU

July 28, 2015

Date

Chen-Yueh Kung  
Chen-Yueh KUNG

July 28, 2015

Date